ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. Il international and Par	PC, Bannock	burn, Illinois. A	ll rights reserved un tions.	nder both	This docume level parts, t	ent is a decla the declaratio	ration of the	substances ses all lowe	within the r er level mate	manufacture rials for whi	r listed ite ich the ma	em. Note: nufacture	if the item is an as er has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information				
Supplier Information															
Company name* Co			Company unique ID			Unique ID Authority					Response Date*				
onsemi							ſ				2024-05-10				
Contact Name Title - O			tle - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative* Tit			Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective D	tive Date Version Manufacturing Site		ng Site	W	veight*	UOM	Unit Type		
	MC74H	C175ADTR2G	LOG CMOS D FLIP FLOP QUAD		AD	2024-05-10			PH4		4.	5.4	mg	Each	
Manufacturing Proccess Information	ion					1								I	
Terminal Plating / Grid Array Ma	terial '	Ferminal Base A	Alloy J	J-STD-020 MSL Rati		Peak Process Body Ter		Temperatu	erature Max Time at Peak T		Temperature Number of Reflow Cycles		eles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1				260		C	30 sec		second	seconds 3			
Comments															
evel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds												
for more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach	1.32	mg	Supplier	Silver (Ag)	7440-22-4		0.99	mg
			Supplier	Epoxy resins	129915-35-1		0.33	mg
Lead Frame	20.76	mg	Supplier	Iron (Fe)	7439-89-6		0.3944	mg
			Supplier	Copper (Cu)	7440-50-8		20.3656	mg
Mold Compound-Black	19.0	mg		Epoxy resin	proprietary data		0.95	mg
			Supplier	Phenolic Resin	Proprietary Data		0.95	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.38	mg
			Supplier	Carbon Black (C)	1333-86-4		0.095	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		16.625	mg
Plating	2.12	mg	Supplier	Palladium (Pd)	7440-05-3		0.1611	mg
			В	Nickel (Ni)	7440-02-0		1.9292	mg
			Supplier	Gold (Au)	7440-57-5		0.0297	mg
Wire Bond - Cu	0.2	mg	Supplier	Copper (Cu)	7440-50-8		0.2	mg